

# **Description**

The NTD25P03LG-HXY uses advanced trench technology

to provide excellent R<sub>DS(ON)</sub>, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

# Battery protection or in other Switching application.

#### **General Features**

 $V_{DS} = -30V I_{D} = -20A$ 

 $R_{DS(ON)}$  < 42 m $\Omega$  @  $V_{GS}$ =10V

#### **Application**

Battery protection

Load switch

Uninterruptible power supply

P-Channel MOSFET

## **Package Marking and Ordering Information**

| Product ID     | Pack            | Marking        | Qty(PCS) |
|----------------|-----------------|----------------|----------|
| NTD25P03LG-HXY | TO-252-2L(DPAK) | 20P03 XXX YYYY | 2500     |

### Absolute Maximum Ratings (T<sub>c</sub>=25°Cunless otherwise noted)

| Symbol                                | Parameter  | Rating     | Units |
|---------------------------------------|--|------------|-------|
| VDS                                   | Drain-Source Voltage   | -30        | V     |
| VGS                                   | Gate-Source Voltage  | ±20        | V     |
| I <sub>D</sub> @T <sub>C</sub> =25°C  | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> | -20        | А     |
| I <sub>D</sub> @T <sub>C</sub> =100°C | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> | -15        | А     |
| IDM                                   | Pulsed Drain Current <sup>2</sup>                            | -50        | А     |
| P <sub>D</sub> @T <sub>C</sub> =25°C  | Total Power Dissipation <sup>4</sup>                         | 29         | W     |
| TSTG                                  | Storage Temperature Range                                    | -55 to 150 | °C    |
| TJ                                    | Operating Junction Temperature Range                         | -55 to 150 | °C    |
| ReJA                                  | Thermal Resistance Junction-ambient <sup>1</sup>             | 75         | °C/W  |
| R <sub>θ</sub> JC                     | Thermal Resistance Junction-Case <sup>1</sup>                | 4.32 °C/W  |       |

#### P-Channel Enhancement Mode MOSFET

# Electrical Characteristics (T<sub>A</sub>=25 ℃ unless otherwise noted)

| Symbol     | Parameter                          | Conditions                     | Min. | Тр   | Max. | Unit  |
|------------|------------------------------------|--------------------------------|------|------|------|-------|
| BVDSS      | Drain-Source Breakdown Voltage     | VGS=0V , ID=-250uA             | -30  |      |      | V     |
| ∆BVDSS/∆TJ | BVDSS Temperature Coefficient      | Reference to 25°C , ID=-1mA    |      | 22   |      | V/°C  |
| RDS(ON)    | Static Drain-Source On-Resistance2 | VGS=-10V , ID=-15A             | 32   | 38   | 42   | mΩ    |
|            |                                    | VGS=-4.5V , ID=-10A            | 48   |      | 58   |       |
| VGS(th)    | Gate Threshold Voltage             | VGS=VDS , ID =-250uA           | -1.0 |      | -2.5 | V     |
| △VGS(th)   | VGS(th) Temperature Coefficient    |                                |      | 4.6  |      | mV/°C |
|            |                                    | VDS=-24V, VGS=0V,              |      |      | -1   |       |
| IDSS       |                                    | TJ=25°C                        |      |      |      |       |
|            | Drain-Source Leakage Current       | VDS=-24V , VGS=0V ,<br>TJ=55°C |      |      | -5   | uA    |
|            |                                    |                                |      |      |      |       |
| IGSS       | Gate-Source                        | VGS=±25V , VDS=0V              |      |      | ±100 | nA    |
|            | LeakageCurrent                     |                                |      |      |      |       |
| gfs        | Forward                            | VDS=-5V , ID=-15A              |      | 19   |      | S     |
|            | Transconductance                   |                                |      |      |      |       |
| Rg         | Gate Resistance                    | VDS=0V , VGS=0V , f=1MHz       |      | 13   |      |       |
| Qg         | Total Gate Charge (-4.5V)          |                                |      | 12.5 |      |       |
| Qgs        | Gate-Source Charge                 | VDS=-15V , VGS=-4.5V , ID=-15A |      | 5.4  |      | nC    |
| Qgd        | Gate-Drain Charge                  | _                              |      | 5    |      | 1     |
| Td(on)     | Turn-On Delay Time                 |                                |      | 4.4  |      |       |
| Tr         | Rise Time                          | VDD=-15V , VGS=-10V , RG=3.3 , |      | 11.2 |      | ns    |
| Td(off)    | Turn-Off Delay Time                | ID=-15A                        |      | 34   |      |       |
| Tf         | Fall Time                          | 1                              |      | 18   |      |       |
| Ciss       | Input Capacitance                  |                                |      | 1345 |      |       |
| Coss       | Output Capacitance                 | VDS=-15V , VGS=0V , f=1MHz     |      | 194  |      | pF    |
| Crss       | Reverse Transfer Capacitance       |                                |      | 158  |      |       |

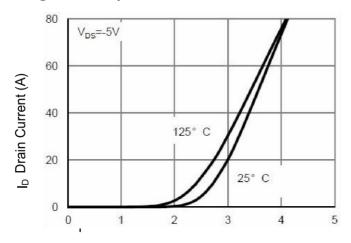
#### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- **3.** Pulse Test: Pulse Width ≤  $300\mu$ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

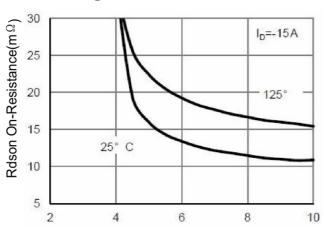


# **Typical Electrical and Thermal Characteristics**

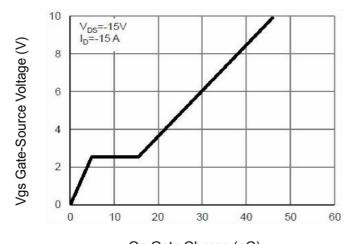
#### **Figure 5 Output Characteristics**



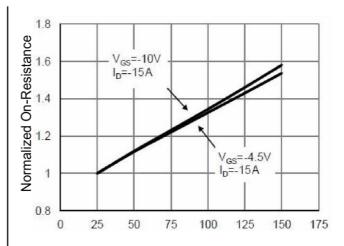
Vgs Gate-Source Voltage (V)
Figure 7 Transfer Characteristics



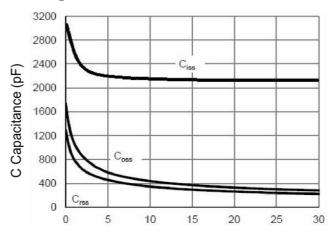
Vgs Gate-Source Voltage (V)
Figure 9 Rdson vs Vgs



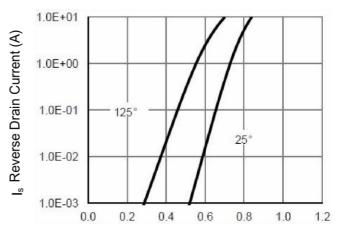
Qg Gate Charge (nC)
Figure 11 Gate Charge



 $T_J$ -Junction Temperature( ${}^{\circ}$ C) Figure 8 Drain-Source On-Resistance



Vds Drain-Source Voltage (V)
Figure 10 Capacitance vs Vds



Vsd Source-Drain Voltage (V)
Figure 12 Source- Drain Diode Forward

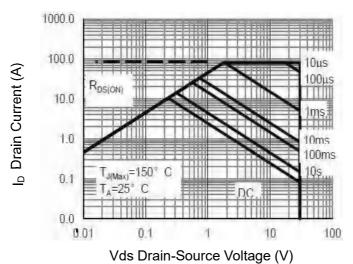
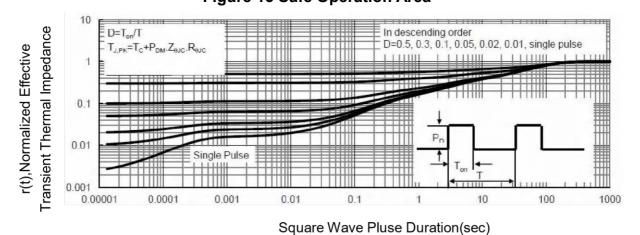


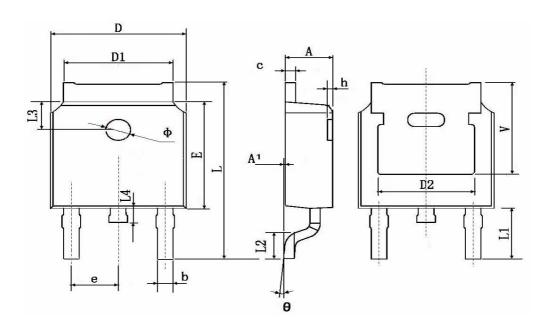
Figure 13 Safe Operation Area



**Figure 14 Normalized Maximum Transient Thermal Impedance** 

#### P-Channel Enhancement Mode MOSFET

# TO-252-2L(DPAK) Package Information



| Symbol | Dimensions In Millimeters |            | Dimensions In Inches |            |  |  |
|--------|---------------------------|------------|----------------------|------------|--|--|
|        | Min.                      | Max.       | Min.                 | Max.       |  |  |
| А      | 2.200                     | 2.400      | 0.087                | 0.094      |  |  |
| A1     | 0.000                     | 0.127      | 0.000                | 0.005      |  |  |
| b      | 0.660                     | 0.860      | 0.026                | 0.034      |  |  |
| С      | 0.460                     | 0.580      | 0.018                | 0.023      |  |  |
| D      | 6.500                     | 6.700      | 0.256                | 0.264      |  |  |
| D1     | 5.100                     | 5.460      | 0.201                | 0.215      |  |  |
| D2     | 4.830                     | 4.830 TYP. |                      | 0.190 TYP. |  |  |
| E      | 6.000                     | 6.200      | 0.236                | 0.244      |  |  |
| е      | 2.186                     | 2.386      | 0.086                | 0.094      |  |  |
| L      | 9.800                     | 10.400     | 0.386                | 0.409      |  |  |
| L1     | 2.900                     | 2.900 TYP. |                      | 0.114 TYP. |  |  |
| L2     | 1.400                     | 1.700      | 0.055                | 0.067      |  |  |
| L3     |                           | 1.600 TYP. |                      | 0.063 TYP. |  |  |
| L4     | 0.600                     | 1.000      | 0.024                | 0.039      |  |  |
| Ф      | 1.100                     | 1.300      | 0.043                | 0.051      |  |  |
| θ      | 0°                        | 8°         | 0°                   | 8°         |  |  |
| h      | 0.000                     | 0.300      | 0.000                | 0.012      |  |  |
| V      | 5.350                     | TYP.       | 0.211 TYP.           |            |  |  |



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